SDFS010A - MARCH 1987 - REVISED OCTOBER 1993

- 3-State Outputs Drive Bus Lines Directly
- Package Options Include Plastic Small-Outline (SOIC) and Shrink Small-Outline (SSOP) Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs

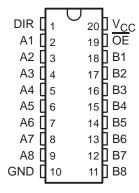
description

These octal bus transceivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction-control (DIR) input. The output enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

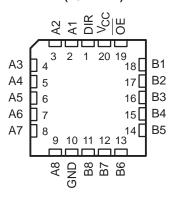
The SN74F245 is available in Tl's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54F245 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F245 is characterized for operation from 0°C to 70°C.

SN54F245 . . . J PACKAGE SN74F245 . . . DB, DW, OR N PACKAGE (TOP VIEW)



SN54F245 . . . FK PACKAGE (TOP VIEW)



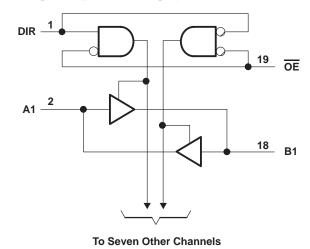
FUNCTION TABLE

INP	UTS	OPERATION			
OE	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	Χ	Isolation			

logic symbol†

OE G3 3EN1[BA] 3EN2[AB] 18 **B**1 \triangleright 2♡ 17 **A2 B2** 16 **A3 B3** 15 Α4 В4 14 **B5** Α5 13 **B6** A6 12 Α7 **B7** 11 **A8 B8**

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}		0.5 V to 7 V
Input voltage range, V _I (except I/O port	s) (see Note 1)	–1.2 V to 7 V
Input current range		30 mA to 5 mA
Voltage range applied to any output in t	the disabled or power-off sta	te0.5 V to 5.5 V
Voltage range applied to any output in t	the high state	0.5 V to V _{CC}
Current into any output in the low state:	: SN54F245 (A1 thru A8)	40 mA
	SN54F245 (B1 thru B8)	96 mA
	SN74F245 (A1 thru A8)	48 mA
	SN74F245 (B1 thru B8)	128 mA
Operating free-air temperature range:	SN54F245	–55°C to 125°C
	SN74F245	0°C to 70°C
Storage temperature range		–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions

			S	SN54F245			SN74F245			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage				5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V		
V _{IL}	Low-level input voltage			0.8			0.8	V		
ΙΙΚ	Input clamp current			-18			-18	mA		
lau	High-level output current	A1 thru A8			-3			-3	mA	
ЮН	r ligh-level output current	B1 thru B8			- 12			- 15	IIIA	
lo:	Low-level output current	A1 thru A8			20			24	mA	
IOL	Low-level output current	B1 thru B8			48			64	IIIA	
T _A	Operating free-air temperature		-55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER TEST CONDITI		TEST CONDITIONS		S	SN54F245			SN74F245			
		CONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT		
٧IK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
	A1 thru A8	V _{CC} = 4.5 V	I _{OH} = - 1 mA	2.5	3.4		2.5	3.4			
	AT tillu Ao	VCC = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3			
∨он	B1 thru B8	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2					V	
	BT tilla Bo	VCC = 4.5 V	$I_{OH} = -15 \text{ mA}$				2	3.1			
	Any output	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA to } -3 \text{ mA}$				2.7				
	A1 thru A8	V _{CC} = 4.5 V	$I_{OL} = 20 \text{ mA}$		0.3	0.5					
VOL			$I_{OL} = 24 \text{ mA}$					0.35	0.5	V	
I VOL	B1 thru B8	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$		0.38	0.55				V	
	BT tilla Bo		$I_{OL} = 64 \text{ mA}$					0.42	0.55		
11	A and B	V _{CC} = 5.5 V	V _I = 5.5 V			1			1	mA	
<u>'</u>	DIR, OE	VCC = 3.5 V	V _I = 7 V			0.1			0.1	ША	
,+	A and B	V _{CC} = 5.5 V,	V _I = 2.7 V			70			70	Δ	
¹IH [‡]	DIR, OE	VCC = 3.5 v,	V - 2.1 V	20			20			μΑ	
1 +	A and B	V _{CC} = 5.5 V,	V _I = 0.5 V			-0.65			-0.65	mA	
I _{IL} ‡	DIR, OE	VCC = 3.5 V,	V = 0.5 V			- 1.2			- 1.2	IIIA	
los§	A1 thru A8	V _{CC} = 5.5 V,	V _O = 0	-60		-150	-60		-150	mA	
1053	B1 thru B8	VCC = 3.3 v,	v () = 0			-225	-100		-225	""	
			Outputs high		70	90		70	90	mA	
ICC		$V_{CC} = 5.5 \text{ V}$	Outputs low		95	120		95	120		
			Outputs disabled	utputs disabled 85 110			85	110			



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

SN54F245, SN74F245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDFS010A - MARCH 1987 - REVISED OCTOBER 1993

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, C_{L} = 50 pF, R_{L} = 500 Ω, T_{A} = 25°C			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω , T_A = MIN to MAX [†]				UNIT
			′F245			SN54F245		SN74F245		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	B or A	1.7	3.8	6	1.2	7.5	1.7	7	ns
t _{PHL}	AOIB		1.7	4.2	6	1.2	7.5	1.7	7	113
^t PZH	ŌĒ	A or B	2.2	4.9	7	1.7	9	2.2	8	ns
t _{PZL}	OE .	AOIB	2.7	5.6	8	2.2	10	2.7	9	115
^t PHZ	ŌĒ	A or B	2.2	4.6	6.5	1.7	9	2.2	7.5	ns
t _{PLZ}			1.2	4.6	6.5	1.2	10	1.2	7.5	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and waveforms are shown in Section 1.







i.com 26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
85511012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8551101RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
8551101SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/34803B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/34803BRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/34803BSA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
SN54F245J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN74F245DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74F245DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F245DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F245DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74F245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F245DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F245DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F245DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74F245N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74F245NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74F245NSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74F245NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54F245FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54F245J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54F245W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame



PACKAGE OPTION ADDENDUM

26-Sep-2005

retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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